

This listing of claims will replace all prior versions, and listings, of claims in the Application:

LISTING OF CLAIMS:

1. (Currently amended) A chip scale package comprising:
 - a leadframe including (1) a die attach pad centrally located therein, said die attach pad having a die attach surface, and (2) a plurality of wire bonding pads peripherally located therein; at least one aperture formed in the die attach surface die attach pad, wherein said aperture is open at said die attach surface;
 - at least one die formed on the die attach surface pad;
 - at least one bonding wire for electrically connecting the at least one die and at least of one of the plurality of wire bonding pads; and
 - a mold compound, wherein said mold compound encapsulates the at least one die and the at least one bonding wire to form a chip scale package, and wherein the mold compound resides in the at least one aperture.
2. (Original) The chip package of claim 1, wherein the aperture is formed fully through the die attach pad.
3. (Original) The chip package of claim 1, wherein the aperture is formed partially through the die attach pad.
4. (Original) The chip package of claim 1, wherein the aperture is formed using a combination of a full etch process and a half etch process.

5. (Original) The chip package of claim 1, wherein the shape of the aperture is one of the following: a rectangle, a square, an oval, a triangle, a circle, or a combination thereof.

6. (Original) The chip package of claim 1, wherein the chip package is a leadframe-based Chip Scale Package.

7. (Original) The chip package of claim 1, wherein the aperture includes a plurality of apertures formed around the at least one die.

8. (Currently Amended) The chip package of claim 7, wherein the at least one die ~~includes~~ comprises at least a first and a second die ~~dies~~, and at least one of the plurality of apertures is disposed between the first die and the second die ~~dies~~.

9. (Canceled)

10. (Withdrawn) A method of providing a chip package, comprising the steps of:
 providing a leadframe including a die attach pad centrally located therein and a plurality of wire bonding pads peripherally located therein;
 providing at least one aperture in the die attach pad;
 providing at least one die on the die attach pad;
 providing at least one bonding wire for electrically connecting the die and the wire bonding pads; and

providing a mold compound for encapsulating the die and the bonding wire to form a chip package, wherein the mold compound is formed in the aperture.

11. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes: forming the aperture fully through the die attach pad.

12. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes: forming the aperture partially through the die attach pad.

13. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes: forming the aperture through the die attach pad using a combination of a full etch process and a half etch process.

14. (Withdrawn) The method of claim 10, wherein the shape of the aperture is one of the following: a rectangle, a square, an oval, a triangle, a circle, or a combination thereof.

15. (Withdrawn) The method of claim 10, wherein the chip package is a leadframe-based Chip Scale Package.

16. (Withdrawn) The method of claim 10, wherein the aperture includes a plurality of apertures formed around the at least one die.

17. (Withdrawn) The method of claim 16, wherein the at least one die includes a plurality of dies, and at least one of the plurality of apertures is disposed between the plurality of dies.

18. (Withdrawn) The method of claim 10, wherein the aperture extends horizontally, vertically, or diagonally.